

Electronic Patent Application Fee Transmittal

Application Number:	10553647			
Filing Date:	14-Oct-2005			
Title of Invention:	Resin composition for mold used in forming micropattern, and method for fabricating organic mold therefrom			
First Named Inventor/Applicant Name:	Tae Wan Kim			
Filer:	Eugene Lieberstein/Audrey de Souza			
Attorney Docket Number:	DE1657			
Filed as Small Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 2 months with \$0 paid	2252	1	245	245

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	2801	1	405	405
Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				830